Authorized Representative* Title - Representative Phone - Representative* Email - Representative*	assembly with low g responsibility.		
Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Onsem Weight* UOM Manufacturing Proccess Information Terminal Plating / Grid Array Material			
Title - Contact Name Product-Env-Stewards Uthorized Representative* Product-Env-Stewards Product-Env-Stewards@onsem Requester Item Number Mfr Item Number Mfr Item Name Effective Date Effective Date Version Manufacturing Site Weight* UOM Anufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow of			
Title - Contact Product-Env-Stewards Prod	Response Date*		
Product-Env-Stewards uthorized Representative* Title - Representative Product-Env-Stewards Pr			
Title - Representative Phone - Representative Phone - Representative Product Envisor Compliance NA Product Env-Stewards © onsem Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM STK5C4U332J-E 3phase inverter HIC 2023-06-08 VN2 4800.0 mg Manufacturing Proccess Information Manufacturing Proccess Information Manufacturing Proccess Information Manufacturing Proccess Body Temperature Max Time at Peak Temperature Number of Reflow of Reflow (National Pating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow (National Pating / Grid Array Material Nation	Email - Contact*		
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Requester Item Number	Email - Representative*		
STK5C4U332J-E 3phase inverter HIC 2023-06-08 VN2 4800.0 mg Ianufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow	Product-Env-Stewards@onsemi.com		
Interest of the contract of the	Unit Type		
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow	Each		
Matte III (Sn) - annealed CU Alloy NA U C 30 Seconds 3	/cles		
omments			
or more information regarding material composition please refer to page 3			

RoHS Material Composition Declaration		Declaration 7	Гуре *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and believe as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence										
RoHS Declaration * 4 - Item(s	does not contain RoHS restricted substances	per the definition above except for sele	ted exemptions	Supplier Acceptance	* Accepted					
Exemption: 7c-I Electrical and electronic co	omponents containing lead in a glass or cera	mic other than dielectric ceramic in	apacitors, e.g. piezoelect	ronic devices, or in a glass or co	eramic matrix compound.					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	E								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	1230.07	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		15.3759	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		60.6424	mg
			В	Nickel (Ni)	7440-02-0		2.0911	mg
			Supplier	Acrylic resins	Proprietary Data		0.861	mg
			Supplier	Copper (Cu)	7440-50-8		82.6607	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.615	mg
			Supplier	Aluminum (Al)	7429-90-5		1067.8237	mg
Chip Parts	14.02	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.2842	mg
			Supplier	Silver (Ag)	7440-22-4		0.4627	mg
			Supplier	Epoxy resins	129915-35-1		0.1781	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068- 38-6		0.0084	mg
			Supplier	Tin (Sn)	7440-31-5		0.4767	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2748	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		5.0584	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0196	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.5709	mg
			В	Nickel (Ni)	7440-02-0		1.7665	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.0252	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0014	mg
			Supplier	Copper (Cu)	7440-50-8		0.8931	mg
Die	11.21	mg	Supplier	Silicon (Si)	7440-21-3		11.21	mg
Lead Frame	465.65	mg	Supplier	Tin (Sn)	7440-31-5		0.2794	mg
			Supplier	Copper (Cu)	7440-50-8		465.3706	mg
Mold Compound-Black	3071.21	mg		Phenolic Resin	proprietary data		184.2726	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		307.121	mg
			Supplier	Carbon Black (C)	1333-86-4		15.356	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		168.9165	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		2395.5437	mg
Plating	1.2	mg	Supplier	Tin (Sn)	7440-31-5		0.7429	mg
			В	Nickel (Ni)	7440-02-0		0.4571	mg

Solder Ball	3.59	mg	Supplier	Silver (Ag)	7440-22-4	0.1002	mg
			Supplier	Tin (Sn)	7440-31-5	3.4694	mg
			В	Antimony (Sb)	7440-36-0	0.0029	mg
			Supplier	Copper (Cu)	7440-50-8	0.0176	mg
Wire Bond	3.05	mg	Supplier	Silicon (Si)	7440-21-3	0.0043	mg
			Supplier	Aluminum (Al)	7429-90-5	3.0457	mg